

What is claimed is:

1. A semiconductor device comprising:

a semiconductor chip;

a wiring board joined to one surface of the  
5 semiconductor chip and electrically connected to the  
semiconductor chip; and

a warp preventing board joined to the other surface  
of the semiconductor chip and composed of the same  
material as that of the wiring board.

10 2. The semiconductor device according to claim 1,  
wherein

an external connection member for surface mounting  
is arranged on a surface, facing away from the  
semiconductor chip, of the wiring board.

15 3. The semiconductor device according to claim 1,  
wherein

the warp preventing board is another wiring board,  
another semiconductor chip electrically connected  
to the warp preventing board being joined to a surface,  
20 facing away from the semiconductor chip, of the warp  
preventing board.

4. The semiconductor device according to claim 1,  
wherein

a wiring material for electrically connecting the  
25 wiring board and the warp preventing board is interposed

SC7  
therebetween.

add  
a<sup>2</sup>7

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